

TOSHIBA CMOS Linear Integrated Circuit Silicon Monolithic

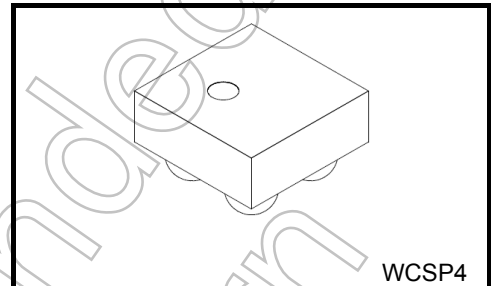
# TCK106G, TCK107G, TCK108G

## 1.0 A Load Switch IC with Slew Rate Control Driver in Ultra Small Package

The TCK106G, TCK107G and TCK108G are load switch ICs for a general power management with slew rate control driver, featuring low switch ON resistance and wide input voltage operation from 1.1 to 5.5 V.

Switch ON resistance is only 49 mΩ typical at 5.0 V, 500 mA condition and output current is available on 1.0 A. TCK107G and TCK108G feature output auto-discharge function.

These devices are available in 0.4 mm pitch ultra small package WCSP4 (0.79 mm x 0.79 mm, t: 0.5 mm) .Thus this devices is ideal for portable applications that require high-density board assembly such as cellular phone.

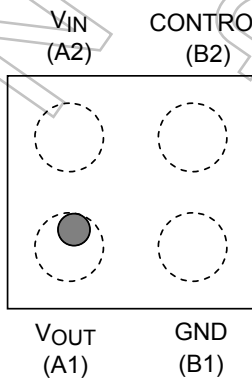


Weight: 0.7 mg (typ.)

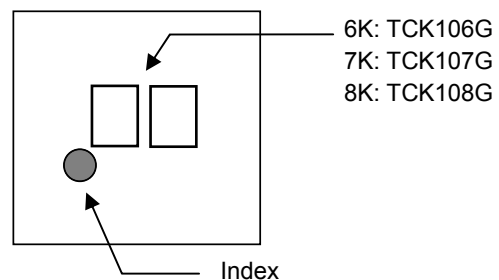
### Feature

- Wide input voltage operation:  $V_{IN} = 1.1$  to 5.5 V
- High output current:  $I_{OUT} = 1.0$  A
- Low ON resistance :
  - $R_{ON} = 49$  mΩ (typ.) at  $V_{IN} = 5.0$  V, 500 mA
  - $R_{ON} = 57$  mΩ (typ.) at  $V_{IN} = 3.3$  V, 500 mA
  - $R_{ON} = 83$  mΩ (typ.) at  $V_{IN} = 1.8$  V, 500 mA
  - $R_{ON} = 143$  mΩ (typ.) at  $V_{IN} = 1.2$  V, 200 mA
  - $R_{ON} = 176$  mΩ (typ.) at  $V_{IN} = 1.1$  V, 200 mA
- Built in Slew rate control driver
- Built in Auto-discharge (TCK107G and TCK108G)
- Active High and Pull down connection between CONTROL and GND (TCK106G and TCK107G)
- Active Low (TCK108G)
- Ultra small package : WCSP4 (0.79 mm x 0.79 mm, t: 0.5 mm)

### Pin Assignment(Top view)



### Top marking



Start of commercial production  
2013-02

## Absolute Maximum Ratings (Ta = 25°C)

Characteristics	Symbol	Rating	Unit
Input voltage	$V_{IN}$	6.0	V
Control voltage	$V_{CT}$	-0.3 to 6.0	V
Output voltage	$V_{OUT}$	-0.3 to $V_{IN} + 0.3$	V
Output current	$I_{OUT}$	DC 1.0	A
Power dissipation	$P_D$	800 (Note 1)	mW
Operating temperature range	$T_{opr}$	-40 to 85	°C
Junction temperature	$T_j$	150	°C
Storage temperature	$T_{stg}$	-55 to 150	°C

Note : Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings and the operating ranges. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

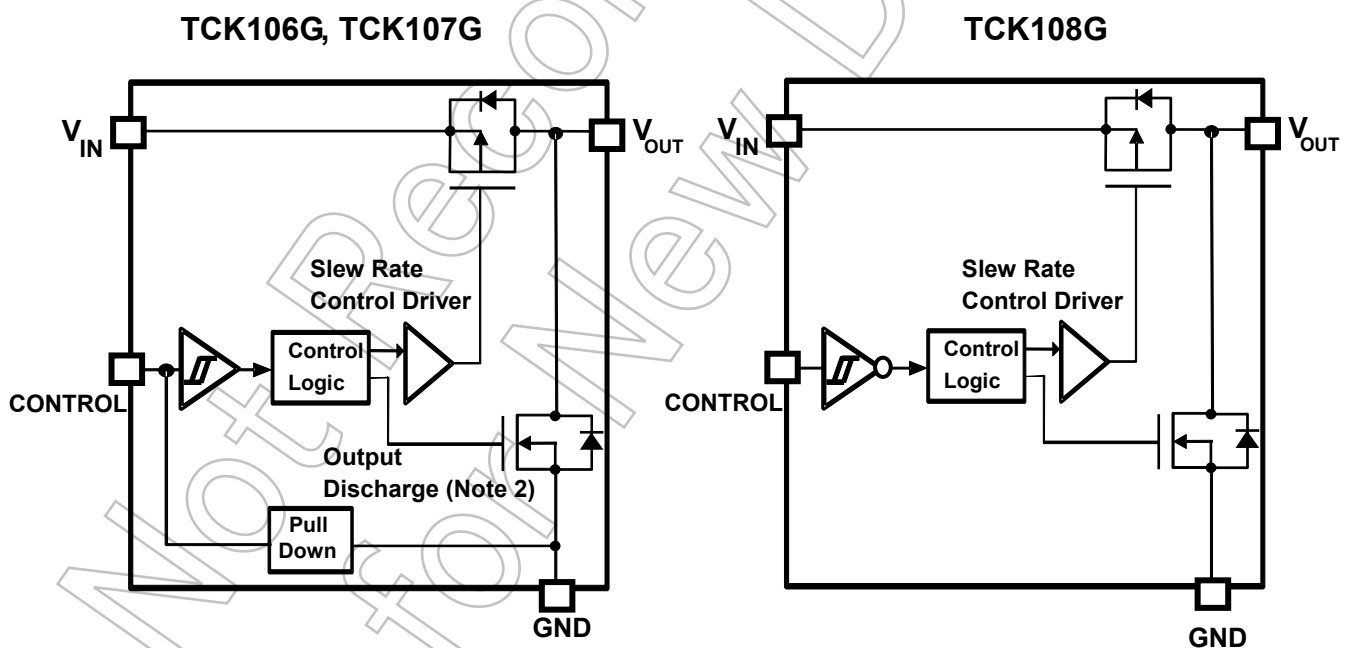
Note1: Rating at mounting on a board

(Glass epoxy board dimension: 40mm x 40mm, both sides of board)

Metal pattern ratio: a surface approximately 50%, the reverse side approximately 50%

Through hole: diameter 0.5mm x 28)

## Block Diagram



Note 2: TCK107G only

## Electrical Characteristics

### DC Characteristics (Ta = -40 to 85°C)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Input voltage	V <sub>IN</sub>	—	1.1	—	5.5	V
CONTROL High-level input voltage	V <sub>IH</sub>	V <sub>IN</sub> = 1.1 to 5.5 V	0.9	—	—	V
CONTROL Low-level input voltage	V <sub>IL</sub>	V <sub>IN</sub> = 1.1 to 5.5 V	—	—	0.4	V
Quiescent current (ON state)	I <sub>Q</sub>	V <sub>IN</sub> = V <sub>CT</sub> = 5.5 V, I <sub>OUT</sub> = 0 mA	TCK106G TCK107G	80	200	nA
		V <sub>IN</sub> = 5.5 V, V <sub>CT</sub> = 0 V, I <sub>OUT</sub> = 0 mA	TCK108G			
Standby current (OFF state)	I <sub>Q(OFF)</sub>	V <sub>IN</sub> = 5.5 V, V <sub>CT</sub> = 0 V, V <sub>OUT</sub> = OPEN (Note 3)	TCK106G TCK107G	50	135	nA
		V <sub>IN</sub> = V <sub>CT</sub> = 5.5 V, V <sub>OUT</sub> = OPEN (Note 3)	TCK108G			
OFF-state switch current	I <sub>SD(OFF)</sub>	V <sub>IN</sub> = 5.5 V, V <sub>CT</sub> = 0 V, V <sub>OUT</sub> = GND	TCK106G TCK107G	14	1000	nA
		V <sub>IN</sub> = V <sub>CT</sub> = 5.5 V, V <sub>OUT</sub> = GND	TCK108G			
On resistance	R <sub>ON</sub>	V <sub>IN</sub> = 5.0 V, I <sub>OUT</sub> = -0.5 A	—	49	73	mΩ
		V <sub>IN</sub> = 3.3 V, I <sub>OUT</sub> = -0.5 A	—	57	84	
		V <sub>IN</sub> = 1.8 V, I <sub>OUT</sub> = -0.5 A	—	83	123	
		V <sub>IN</sub> = 1.2 V, I <sub>OUT</sub> = -0.2 A	—	143	225	
		V <sub>IN</sub> = 1.1 V, I <sub>OUT</sub> = -0.2 A	—	176	—	
Discharge on resistance	R <sub>SD</sub>	— (TCK107G and TCK108G)	—	100	—	Ω

Note 3 : Except I<sub>SD(OFF)</sub> OFF-state switch current

## AC Characteristics (Ta = 25°C)

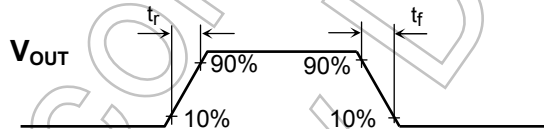
V<sub>IN</sub> = 1.2 V

Characteristics	Symbol	Test Condition (Figure 1)	Min	Typ.	Max	Unit	
V <sub>OUT</sub> rise time	t <sub>r</sub>	R <sub>L</sub> = 500 Ω, C <sub>L</sub> = 0.1 μF	—	290	—	μs	
V <sub>OUT</sub> fall time	t <sub>f</sub>	R <sub>L</sub> = 500 Ω, C <sub>L</sub> = 0.1 μF	TCK107G	—	30	—	μs
			TCK108G	—	104	—	
Turn on delay	t <sub>ON</sub>	R <sub>L</sub> = 500 Ω, C <sub>L</sub> = 0.1 μF	—	305	—	μs	
Turn off delay	t <sub>OFF</sub>	R <sub>L</sub> = 500 Ω, C <sub>L</sub> = 0.1 μF	—	5	—	μs	

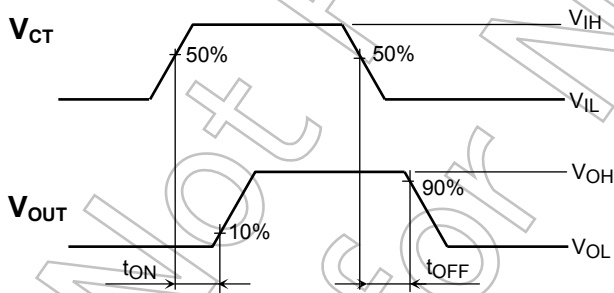
V<sub>IN</sub> = 3.3 V

Characteristics	Symbol	Test Condition (Figure 1)	Min	Typ.	Max	Unit	
V <sub>OUT</sub> rise time	t <sub>r</sub>	R <sub>L</sub> = 500 Ω, C <sub>L</sub> = 0.1 μF	—	130	—	μs	
V <sub>OUT</sub> fall time	t <sub>f</sub>	R <sub>L</sub> = 500 Ω, C <sub>L</sub> = 0.1 μF	TCK107G	—	25	—	μs
			TCK108G	—	110	—	
Turn on delay	t <sub>ON</sub>	R <sub>L</sub> = 500 Ω, C <sub>L</sub> = 0.1 μF	—	100	—	μs	
Turn off delay	t <sub>OFF</sub>	R <sub>L</sub> = 500 Ω, C <sub>L</sub> = 0.1 μF	—	10	—	μs	

## AC Waveform



TCK106G, TCK107G



TCK108G

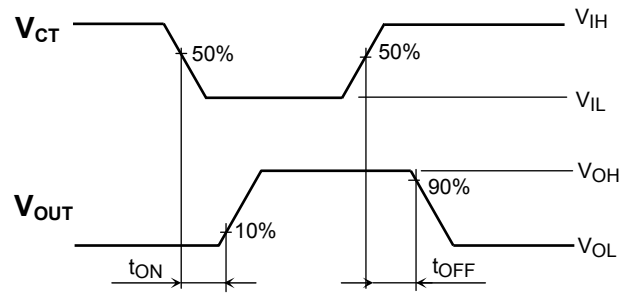
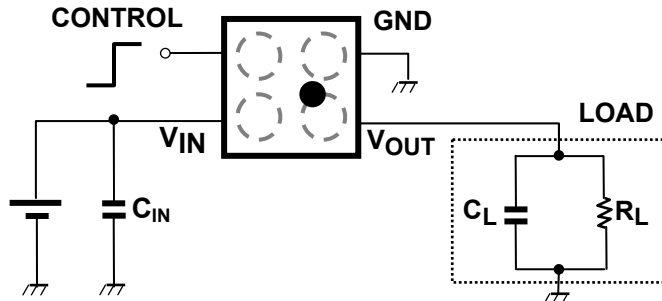


Figure 1 t<sub>r</sub>, t<sub>f</sub>, t<sub>ON</sub>, t<sub>OFF</sub> Waveforms

## Application Note

### 1. Application circuit example (top view)

The figure below shows the recommended configuration for TCK106G, TCK107G and TCK108G.



Part number	Control voltage	IC Operation
TCK106G TCK107G	HIGH	ON
	LOW	OFF
	OPEN	OFF
TCK108G	HIGH	OFF
	LOW	ON

#### 1) Input capacitor

An input capacitor ( $C_{IN}$ ) is not necessary for the guaranteed operation of TCK106G, TCK107G and TCK108G. However, it is recommended to use input capacitors to reduce voltage drop due to sharp changes in output current and also for improved stability of the power supply. When used, place  $C_{IN}$  as close to  $V_{IN}$  pin to improve stability of the power supply. Also, due to the  $C_{IN}$  selected,  $V_{IN} < V_{OUT}$  may occur, causing a reverse current to flow through the body diode of the pass-through p-ch MOSFET of the load switch IC. In this case, a higher value for  $C_{IN}$  as compared to  $C_L$  is recommended.

#### 2) Output capacitor

An output capacitor ( $C_{OUT}$ ) is not necessary for the guaranteed operation of TCK106G, TCK107G and TCK108G. However, there is a possibility of overshoot or undershoot caused by output load transient response, board layout and parasitic components of load switch IC. In this case, an output capacitor with  $C_{OUT}$  more than  $0.1\mu F$  is recommended.

#### 3) Control pin

A control pins for TCK106G and TCK107G are both Active High and TCK108G is Active Low. These controls both the pass-through p-ch MOSFET and the discharge n-ch MOSFET (except TCK106G), operated by the control voltage and Schmitt trigger. When the control voltage level is High (Low; TCK108G), p-ch MOSFET is ON state and n-ch MOSFET is OFF state. When control voltage level is Low (High; TCK108G), and the state of the MOSFETs is reversed. Also, pull down resistance equivalent to a few  $M\Omega$  is connected between CONTROL and GND, thus the load switch IC is in OFF state even when CONTROL pin is OPEN(except TCK108G). In addition, CONTROL pin has a tolerant function such that it can be used even if the control voltage is higher than the input voltage.

**2. Power Dissipation**

Power dissipation is measured on the board condition shown below.

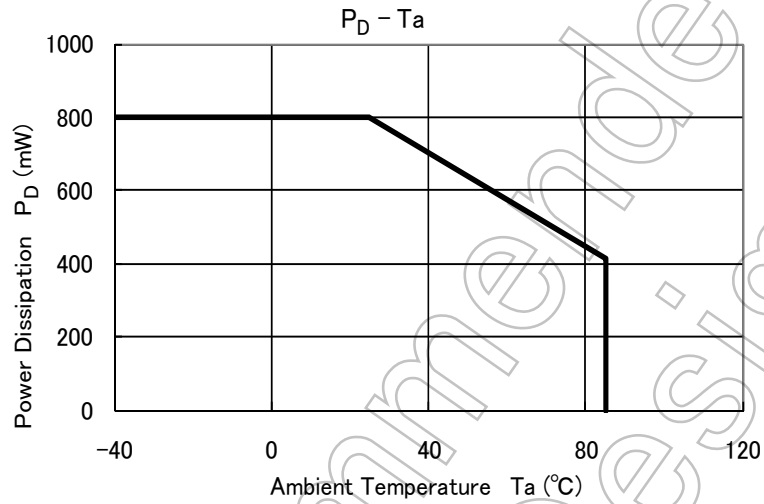
[The Board Condition]

Board material: Glass epoxy (FR4)

Board dimension: 40mm x 40mm (both sides of board), t=1.8mm

Metal pattern ratio: a surface approximately 50%, the reverse side approximately 50%

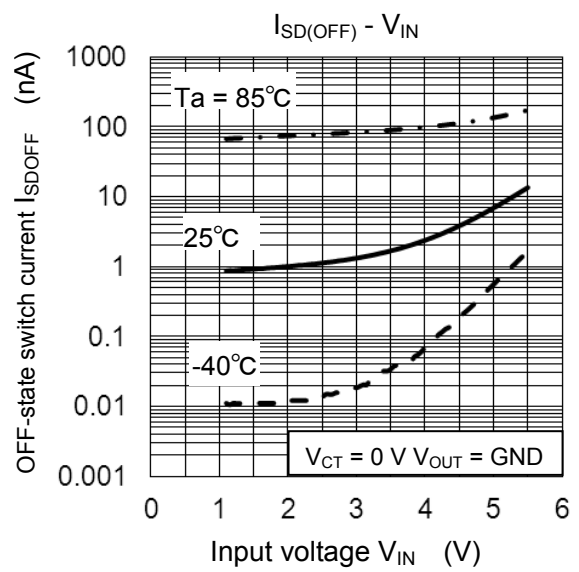
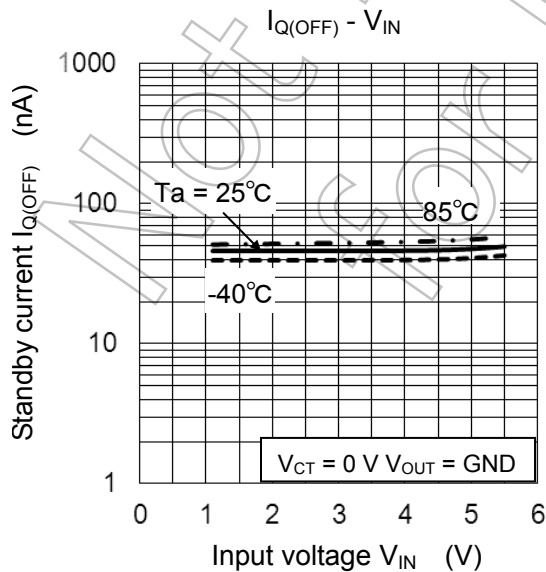
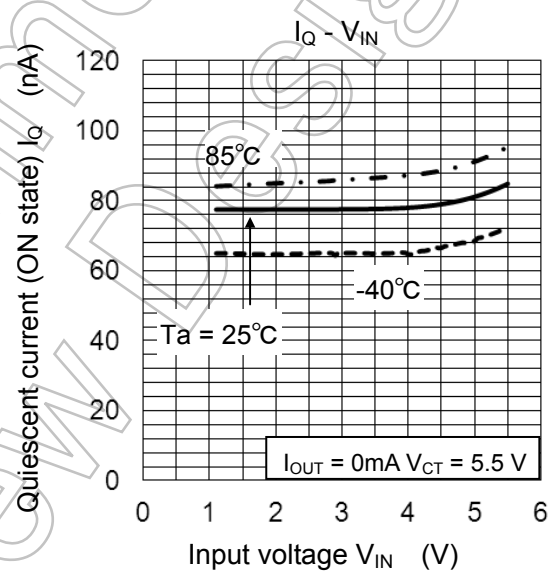
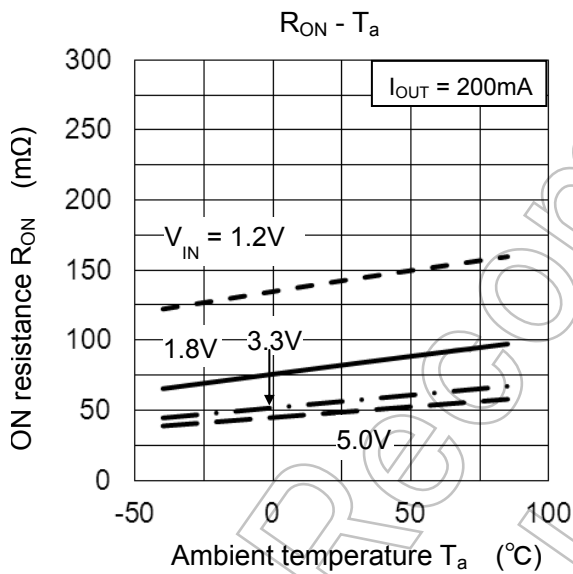
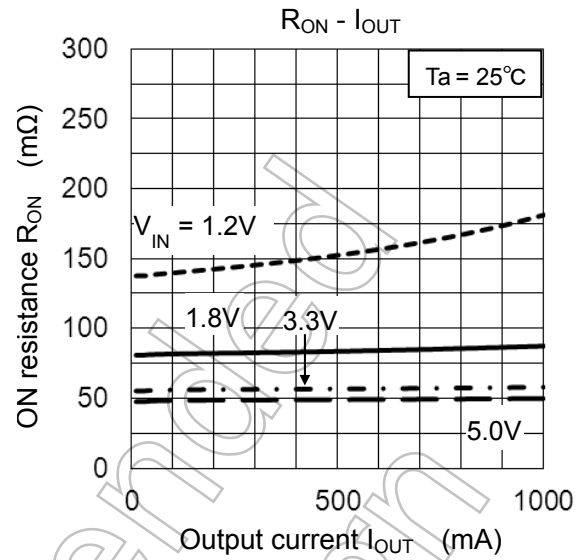
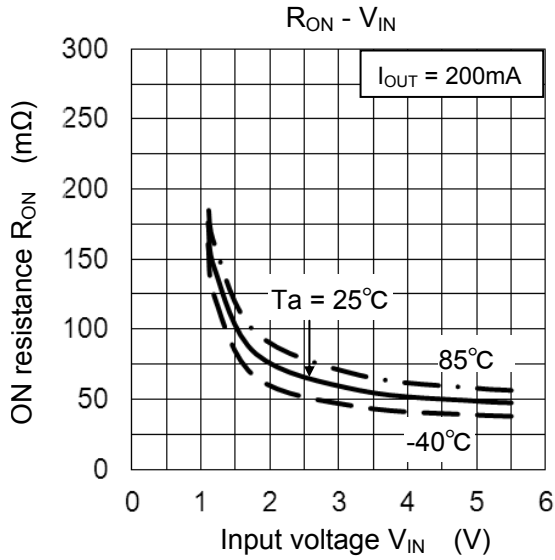
Through hole: diameter 0.5mm x 28



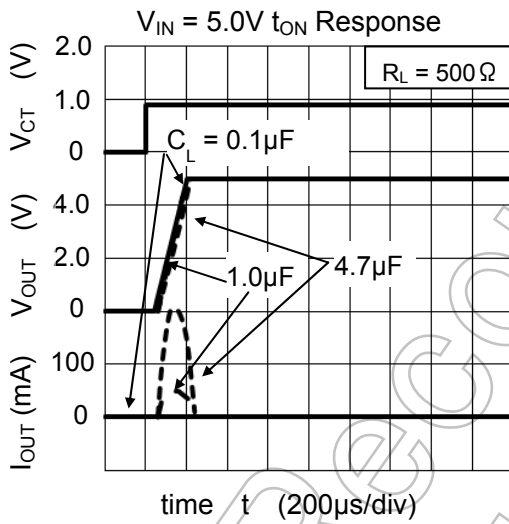
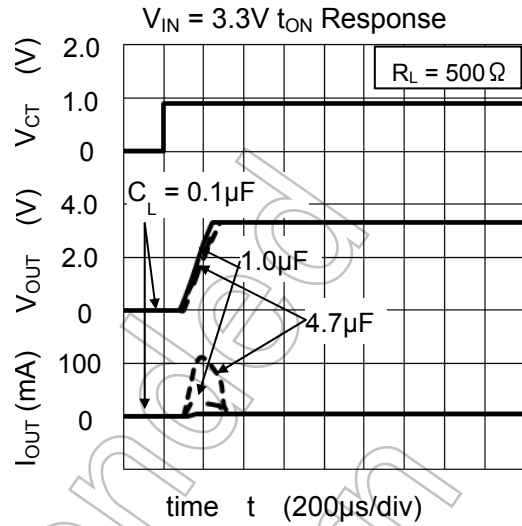
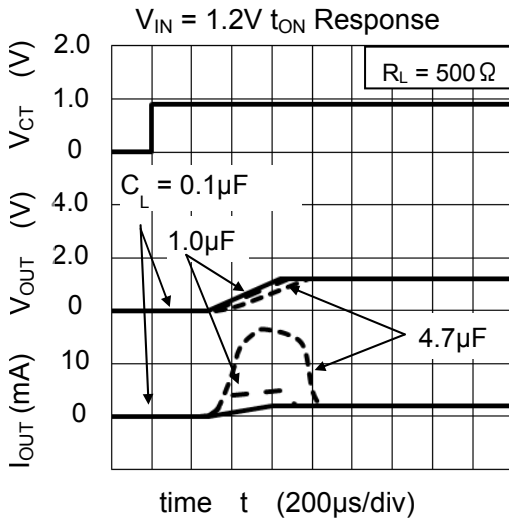
Please allow sufficient margin when designing a board pattern to fit the expected power dissipation. Also take into consideration the ambient temperature, input voltage, output current etc and applying the appropriate derating for allowable power dissipation during operation.

Not Recommended for New Design

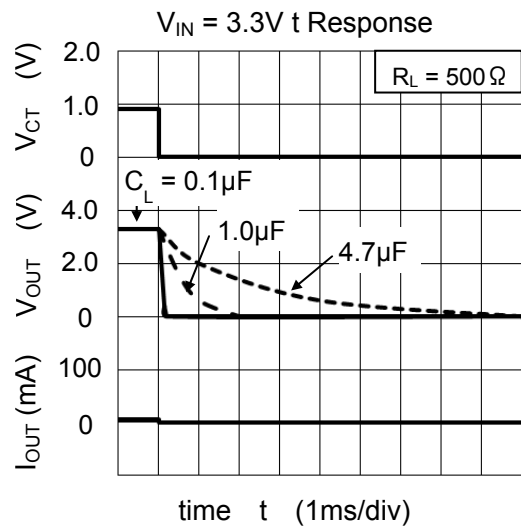
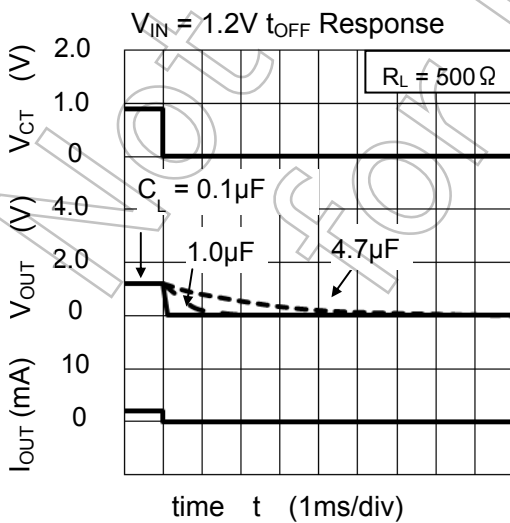
**Representative Common Characteristics**



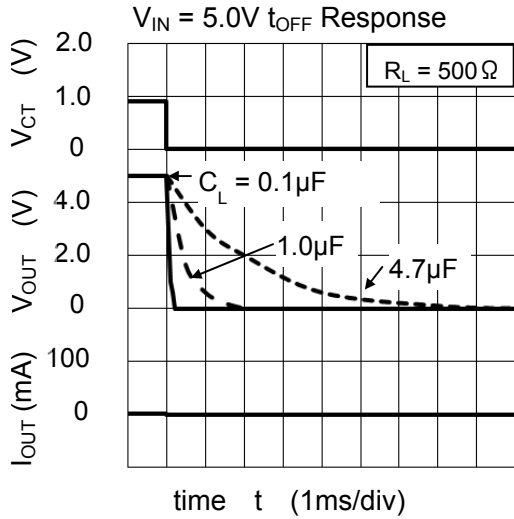
**TCK107G  $t_{ON}$  Response**



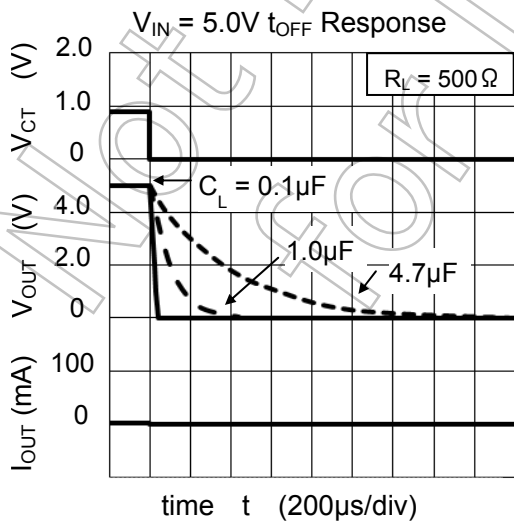
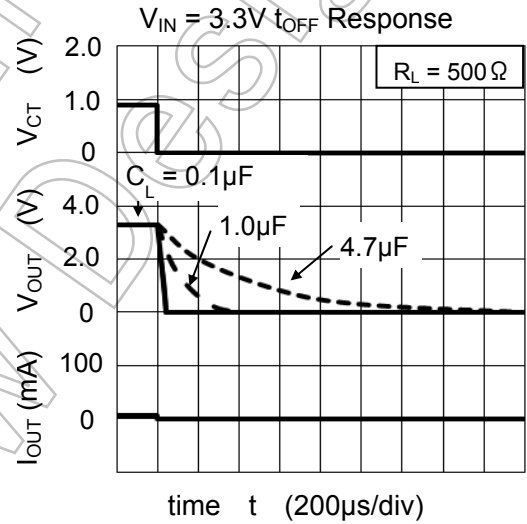
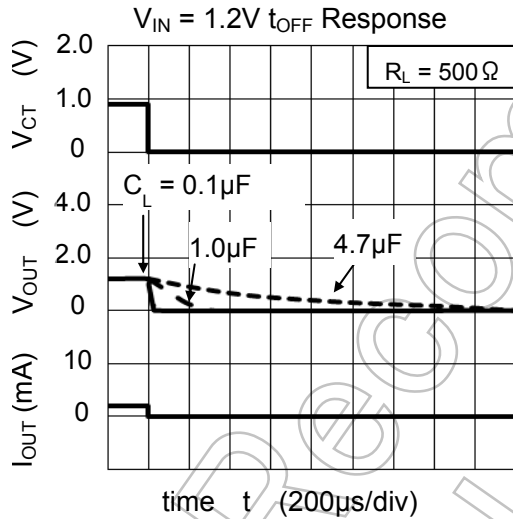
**TCK106G  $t_{OFF}$  Response**







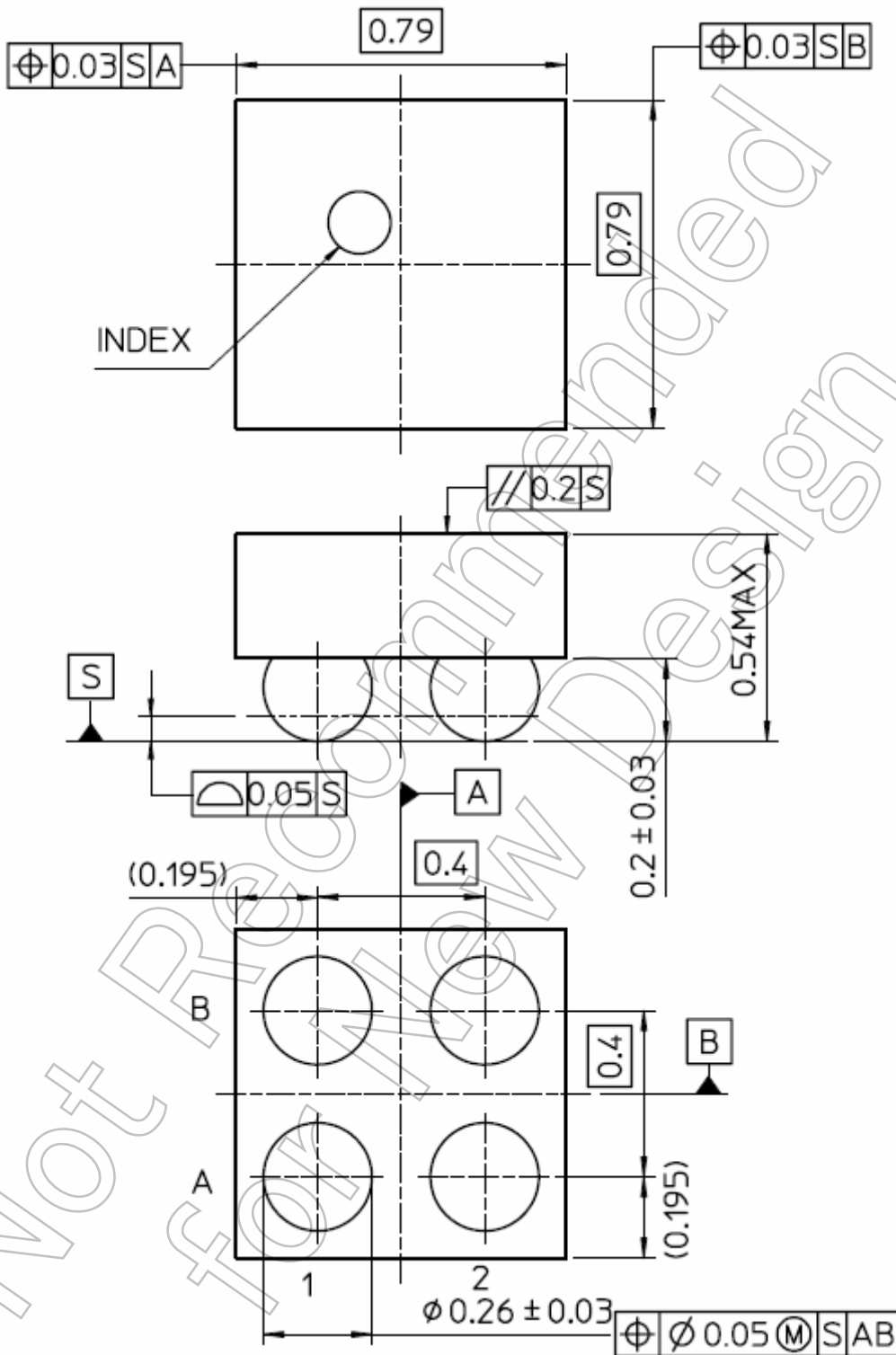
**TCK107G**  $t_{OFF}$  Response



**Package Dimensions**

WCSP4

Unit : mm



Weight : 0.7 mg ( typ.)

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